



- NOTE**
1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRON INCH (1.5 MICRON) MIN THK OVER 100 MICRON INCH (250 MICRON) NOM. THICKNESS OF NICKEL UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
 2. FLATNESS PERTAINS METALLIZED PAD ONLY
 3. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 5 NANO AMPS AT 100V D.C
4. NO PIN CONNECTED TO SEAL AREA AND DIE ATTACH PAD. (ZERO GROUND)

MODIFICATIONS	CHANGED: .060 ^{±0.006} → .060 ^{±0.005} NOTE: 1 79.8.23 R U 0.11	NAME	24 LEAD CHIP CARRIER		TOLERANCES:	FSC-90387 FC-20CA8.2	
	CHANGED: BONDING PAD, SOLDER PAD	SCALE	10/1		UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED
	CHANGED: .020 ^{REF} → .012 ^{REF} MATERIAL	MATERIAL	KYOCERA A-440 ^Δ		± 1%	APPROVED	DATE
	CHANGED: .294 ^{±0.006} → .285 ^{±0.005} .022 ^{MIN} → .0175 ^{MIN} 79.7.26 R U 0.11	DATE	DRAWN	CHECKED	APPROVED	NLT ±0.05 (0.13)	79.7.2
CHANGE	KYOTO CERAMIC CO., LTD.			KYOTO JAPAN	PB-92234		